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*Focus Issue on Electrochemical Processing for Interconnects*



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## Table of Contents

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**Commentary**

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**Electrochemical Processing of Interconnects**

- Thomas. P. Moffat, Daniel Josell ..... Y7

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**Electrochemical/Electroless Deposition**

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**Additives for Bottom-up Copper Plating from an Alkaline Complexed Electrolyte**

- Aniruddha Jai, Rohan Akolkar, Uziel Landau ..... D3001

**Autocatalysis during Electroless Copper Deposition using Glyoxylic Acid as Reducing Agent**

- Lu Yu, Lian Guo, Robert Preisser, Rohan Akolkar ..... D3004

**Superfilling Damascene Trenches with Gold in a Sulfite Electrolyte**

- D. Josell, T. P. Moffat ..... D3009

**Real-Time Observation of Cu Electroless Deposition: Adsorption Behavior of PEG during Cu Electroless Deposition**

- Taeoh Lim, Kyung Ju Park, Myung Jun Kim, Hyo-Chol Koo, Kwang Hwan Kim, Seunghoe Choe, Young-Soo Lee, Jae Jeong Kim ..... D3015

**Accelerator Screening by Cyclic Voltammetry for Microvia Filling by Copper Electroplating**

- Yong-Da Chiu, Wei-Ping Dow ..... D3021

**Characterization of Through-Hole Filling by Copper Electroplating Using a Tetrazolium Salt Inhibitor**

- Guan-Ye Lin, Jhih-Jyun Yan, Ming-Yao Yen, Wei-Ping Dow, Su-Mei Huang ..... D3028

**Extreme Bottom-up Filling of Through Silicon Vias and Damascene Trenches with Gold in a Sulfite Electrolyte**

- D. Josell, T. P. Moffat ..... D3035

**Mechanism of Co Liner as Enhancement Layer for Cu Interconnect Gap-Fill**

- M. He, X. Zhang, T. Nogami, X. Lin, J. Kelly, H. Kim, T. Spooner, D. Edelstein, L. Zhao ..... D3040

**Enhanced Grain Growth of Electroplated Copper on Cobalt-Containing Seed Layer**

- Q. Huang, B. C. Baker-O'Neal, C. Cabral Jr., E. Simonyi, V. R. Deline, M. Hopstaken ..... D3045

**Modeling the Bottom-Up Filling of Through-Silicon vias Through Suppressor Adsorption/Desorption Mechanism**

- Liu Yang, Aleksandar Radisic, Johan Deconinck, Philippe M. Vereecken ..... D3051

**Direct Electrodeposition of Cu on Ru-Al<sub>2</sub>O<sub>3</sub> Layer**

- Myung Jun Kim, Hoe Chul Kim, Soo-Hyun Kim, Seungmin Yeo, Oh Joong Kwon, Jae Jeong Kim ..... D3057

**Quasi-Reversible Interaction of MPS and Chloride on Cu(100) Studied by In Situ STM**

- T. M. T. Huynh, N. T. M. Hai, P. Broekmann ..... D3063

**Morphology, Texture and Twinning Structure of Cu Films Prepared by Low-Temperature Electropoating**

- Chien-Neng Liao, Che-Yi Lin, Chun-Lung Huang, Yi-Sheng Lu ..... D3070

**Direct Copper Plating on Ultra-Thin Sputtered Cobalt Film in an Alkaline Bath**

- Wen-Zhong Xu, Jing-Bo Xu, Hai-Sheng Lu, Jing-Xuan Wang, Zheng-Jun Hu, Xin-Ping Qu ..... D3075

**Pulse-Reverse Electrodeposition of Cu for the Fabrication of Metal Interconnection****I. Effects of Anodic Steps on the Competitive Adsorption of the Additives Used for Superfilling**

- Myung Jun Kim, Taeoh Lim, Kyung Ju Park, Soo-Kil Kim, Jae Jeong Kim ..... D3081

**Pulse-Reverse Electrodeposition of Cu for the Fabrication of Metal Interconnection****II. Enhancement of Cu Superfilling and Leveling**

- Myung Jun Kim, Taeoh Lim, Kyung Ju Park, Soo-Kil Kim, Jae Jeong Kim ..... D3088

**Modeling Macro-Sized, High Aspect Ratio Through-Hole Filling by Multi-Component Additive-Assisted Copper Electrodeposition**

- A. S. Childers, M. T. Johnson, J. Ramirez-Rico, K. T. Faber ..... D3093

<b>Study of Copper Electrodeposition Mechanism on Molybdenum Substrate</b> <i>Dimitri Mercier, Elise Delbos, Hanane El Belghiti, Jackie Vigneron, Muriel Bouttemy, Arnaud Etcheberry</i> ..... D3103	<b>In Situ Surface X-Ray Diffraction Studies of the Influence of the PEG-Cl-Complex on Homoepitaxial Electrodeposition on Cu(001)</b> <i>F. Golks, Y. Gründer, A. Drünklér, J. Roy, J. Stettner, J. Zegenhagen, O. M. Magnussen</i> ..... D3165
<b>Effect of Basicity of Amino Group at Side Chain in Diallylamine-Type Copolymer Additive on Via-Filling by Copper Electrodeposition</b> <i>M. Takeuchi, Y. Yamada, M. Bunya, S. Okada, N. Okamoto, T. Saito, K. Kondo</i> ..... D3110	<b>Electrodeposited Cu Film Morphology on Thin PVD Cu Seed Layers</b> <i>J. Kelly, X. Lin, T. Nogami, O. van der Straten, J. Demarest, J. Li, R. Murphy, X. Zhang, C. Penny, C. Parks, D. Edelstein</i> ..... D3171
<b>Polyvinylpyrrolidones (PVPs): Switchable Leveler Additives for Damascene Applications</b> <i>N. T. M. Hai, J. Furrer, F. Stricker, T. M. T. Huynh, I. Gjuroski, N. Luedi, T. Brunner, F. Weiss, A. Fluegel, M. Arnold, I. Chang, D. Mayer, P. Broekmann</i> ..... D3116	<b>Degradation of Bis(3-sulfopropyl) Disulfide and Its Influence on Copper Electrodeposition for Feature Filling</b> <i>Seunghoe Choe, Myung Jun Kim, Hoe Chul Kim, Sung Ki Cho, Sang Hyun Ahn, Soo-Kil Kim, Jae Jeong Kim</i> ..... D3179
<b>Fabrication of Cu-Ag Interconnection Using Electrodeposition: The Mechanism of Superfilling and the Properties of Cu-Ag Film</b> <i>Myung Jun Kim, Kyung Ju Park, Taeho Lim, Oh Joong Kwon, Jae Jeong Kim</i> ..... D3126	<b>Properties of PEG, PPG and Their Copolymers: Influence on Copper Filling of Damascene Interconnects</b> <i>Kevin Ryan, Kathleen Dunn, Jobert van Eisdien, James Adolf</i> ..... D3186
<b>Real-Time Observation of Cu Electroless Deposition: Effect of EDTA on Removing of Cu Oxide and Adsorption of Formaldehyde</b> <i>Taeho Lim, Kyung Ju Park, Myung Jun Kim, Hyo-Chol Koo, Kwang Hwan Kim, Seunghoe Choe, Jae Jeong Kim</i> ..... D3134	<b>Self-Assembled Monolayer of 3-N, N-Dimethylaminodithiocarbamoyl-1-Propanesulfonic Acid (DPS) Used in Electrodeposition of Copper</b> <i>Ibro Tabakovic, Steve Riemer, Ming Sun</i> ..... D3197
<b>Sidewall Texture and Microstructure of iPVD Copper Seed in Narrow Damascene Trenches</b> <i>Brendan B. O'Brien, Eric Lifshin, K. A. Dunn</i> ..... D3139	<b>Direct Cu Electrodeposition on Ta Using Pd Nanocolloids: Effect of Allyl Alcohol on the Formation of Seed Layer</b> <i>Kwang Hwan Kim, Taeho Lim, Seunghoe Choe, Insoo Choi, Sang Hyun Ahn, Myung Jun Kim, Kyung Ju Park, Min Hyung Lee, Jae Jeong Kim, Oh Joong Kwon</i> ..... D3206
<b>Pulse Electrodeposition of Copper-Manganese Alloy for Application in Interconnect Metallization</b> <i>Aniruddha Joi, Rohan Akolkar, Uziel Landau</i> ..... D3145	<b>PVD Cu Reflow Seed Process Optimization for Defect Reduction in Nanoscale Cu/Low-k Dual Damascene Interconnects</b> <i>K. Motoyama, O. van der Straten, J. Maniscalco, M. He</i> ..... D3211
<b>Through-Hole Filling in a Cu Plating Bath with Functional Insoluble Anodes and Acetic Acid as a Supporting Electrolyte</b> <i>Yu-Tien Lin, Mei-Ling Wang, Chia-Fu Hsu, Wei-Ping Dow, Shih-Min Lin, Jian-Jun Yang</i> ..... D3149	<b>Copper Deep Via Filling with Selective Accelerator Deactivation by Polyethyleneimine</b> <i>Masanori Hayase, Masayuki Nagao</i> ..... D3216
<b>Accelerated Recrystallization in Electrodeposited Dual-Layer Copper Thin Films</b> <i>N. Alshawwreh, M. Militzer, D. Bizzotto, J. C. Kuo</i> ..... D3154	<b>Cu Bottom-Up Filling for Through Silicon Vias with Growing Surface Established by the Modulation of Leveler and Suppressor</b> <i>Myung Jun Kim, Hoe Chul Kim, Seunghoe Choe, Ji Yoon Cho, Donghyung Lee, Il Jung, Won-Seob Cho, Jae Jeong Kim</i> ..... D3221
<b>On the Acceleration of Cu Electrodeposition by TBPS (3,3-thiobis-1-propanesulfonic acid): A Combined Electrochemical, STM, NMR, ESI-MS and DFT Study</b> <i>N. T. M. Hai, J. Furrer, I. Gjuroski, M. P. Bircher, M. Cascella, P. Broekmann</i> ..... D3158	

**Hybrid Method for Metallization  
of Glass Interposers**

*P. Ogutu, E. Fey, P. Borgesen, N. Dimitrov . . . . . D3228*

**Electroless Copper Deposition Using Sn/Ag  
Catalyst on Epoxy Laminates**

*Erdal Uzunlar, Zachary Wilson, Paul A. Kohl . . . . . D3237*

**BEOL Cu CMP Process Evaluation for Advanced  
Technology Nodes**

*Kunaljeet Tanwar, Donald Canaperi, Michael Lofaro,  
Wei-tsu Tseng, Raghuvir Patel, Christopher Penny,  
Christopher Waskiewicz . . . . . D3247*

**Ultra-Low Copper Baths for Sub-35 nm  
Copper Interconnects**

*T. A. Atanasova, L. Carbonell, R. Caluwaerts,  
Zs. Tókei, K. Strubbe, P. M. Vereecken . . . . . D3255*

**Spatial-Temporal Modeling of Extreme Bottom-up  
Filling of Through-Silicon-Vias**

*D. Wheeler, T. P. Moffat, D. Josell . . . . . D3260*

**Resistivity Reduction in Very Narrow Cu Wiring**

*Jin Onuki, Yasushi Sasajima, Kunihiro Tamahashi,  
YiQing Ke, Shohei Terada, Kishio Hidaka, Shinji Itoh . . . . . D3266*

**Use of 3,3-Thiobis(1-propanesulfonate)  
to Accelerate Microvia Filling  
by Copper Electroplating**

*Po-Fan Chan, Yong-Da Chiu, Wei-Ping Dow,  
Klaus Krug, Yuh-Lang Lee, Shueh-Lin Yau . . . . . D3271*

**Ta Surface Chemistry in Aqueous Solutions  
and the Possible Formation of TaTe<sub>2</sub> and TaS<sub>3</sub>**

*Chu Tsang, Youn-Geun Kim, Daniel Gebregziabher,  
John Stickney . . . . . D3278*

**Understanding Residual Stress in Electrodeposited  
Cu Thin Films**

*Eric Chason, Alison Engwall, Fei Pei, Manon Lafouresse,  
Ugo Bertocci, Gery Stafford, Joseph A. Murphy,  
Catherine Lenihan, D. Noel Buckley . . . . . D3285*

**One-Step Fabrication of Copper Thin Films  
on Insulators Using Supercritical Fluid Deposition**

*Takeshi Uejima, Takeshi Momose, Masakazu Sugiyama,  
Eiichi Kondoh, Yukihiro Shimogaki . . . . . D3290*

**Scanning Tunneling Microscopy of Superfilling  
in Formula Containing Chloride, Polyethylene  
Glycol and Bis-3-Sodiumsulfopropyl-Disulfide**

*Yunlin Fu, Sihzh Chen, Shuehlin Yau, Wei-Ping Dow,  
Yuh-Lang Lee . . . . . D3295*

**Through-Silicon-Via (TSV) Filling  
by Electrodeposition of Cu with Pulse Current  
at Ultra-Short Duty Cycle**

*Sanghyun Jin, Geon Wang, Bongyoung Yoo . . . . . D3300*